

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BM Farid RAHMAN	08/20/2013
RECEIVING PARTY DATA	
Name:	University of South Carolina
Street Address:	Osborne Administration Building
Internal Address:	Suite 109
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State/Country:	SOUTH CAROLINA
Postal Code:	29208
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13974659
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Signature:	/Andrew M. Calderon/
Date:	08/23/2013
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 3 source=BUR920120176US1_DeclarationAssignment_USC#page1.tif source=BUR920120176US1_DeclarationAssignment_USC#page2.tif source=BUR920120176US1_DeclarationAssignment_USC#page3.tif	

CH \$40.00 13974659

DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN
APPLICATION DATA SHEET (37 C.F.R. 1.76)

Title of Invention: THREE DIMENSIONAL BRANCHLINE COUPLER USING
THROUGH SILICON VIAS AND DESIGN STRUCTURES

As a below named and undersigned inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

☐ United States application or PCT international application number _____
filed on _____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the
application.

I have reviewed and understand the contents of the application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information
known to me to be material to patentability as defined in 37 CFR Section 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18
U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

(1) Legal Name of Inventor: BM Farid RAHMAN

Signature: Farid Date: 08-20-2013

[IF MORE INVENTORS, ADDITIONAL SIGNATURE PAGE(S) FOLLOWS]

ASSIGNMENT OF WORLDWIDE RIGHTS

WHEREAS, I, BM Farid Rahman, a citizen of Bangladesh, residing in West Columbia, South Carolina, and having a mailing address of University of South Carolina, Osborne Administration Building, Columbia, SC 29208 as assignor, have made an invention entitled **"THREE DIMENSIONAL BRANCHLINE COUPLER USING THROUGH SILICON VIAS AND DESIGN STRUCTURES"** as described in a patent application for U.S. Letters Patent executed by me on even date herewith, which is about to be filed in the U.S. Patent and Trademark Office; and

WHEREAS, University of South Carolina, Osborne Administration Building, Suite 109, Columbia, SC 29208, as assignee, is desirous of securing the entire right, title and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW, THEREFORE, be it known that for good and valuable consideration the receipt of which from assignee is hereby acknowledged, , as assignor, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof, and I hereby authorize and request the Commissioner for Patents of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Agreement.

AND, I HEREBY covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed, and will not execute any agreement in conflict with this Assignment;

AND, I HEREBY further covenant and agree that I will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title of this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

IN WITNESS WHEREOF, Assignor has executed this document on the date indicated below.



BM Farid Rahman

08-20-2013

Date